

Desoldering nozzle round 5.0 mm for HCT-900 - Oki H-D50

Item no. WL30430

Manufacturer Oki

When desoldering multi-pin through-hole parts, the nozzle bore decides whether the solder is drawn out completely or a residue stays in the barrel. The round H-D50 nozzle with a 5.0 mm inner diameter is made for large pads and heavy component leads. It fits straight onto the desoldering handpiece of the Oki HCT-900.

TECHNICAL DATA

Weight

0.1 kg



DESCRIPTION

Round desoldering nozzle for the Oki HCT-900 desoldering system. Its 5.0 mm diameter encloses large pads and heavy leads so the molten solder is pulled out of the plated-through hole completely by the vacuum flow.

BENEFITS

- Inner diameter 5.0 mm for large pads and heavy component leads
- Round shape transfers heat evenly around the whole pad edge
- Changed directly on the handpiece without reconfiguring the station
- Original Oki nozzle with a positive seal to the vacuum channel
- Reduces rework by removing residual solder in one pass

TECHNICAL DATA

Item number	WL30430
Model	H-D50
Manufacturer	OKI
Manufacturer item number	H-D50
Shape	round
Diameter	5.0 mm

APPLICATIONS

Desoldering of connectors, electrolytic capacitors, power semiconductors and other leaded parts with large pads in repair, rework and board overhaul.

COMPATIBILITY AND SCOPE OF DELIVERY

Fits the Oki HCT-900 desoldering system and its desoldering handpiece. Scope of delivery: 1 desoldering nozzle H-D50.